

DYNASOLVE 190

Dynasolve 190 is used for removal of specific silicone and urethane coatings. It is used extensively in the electronics industry.

General

Dynasolve 190 was developed to fill the need for a selective room temperature solvent for Dow Corning 3140 RTV silicone and Conap 1155 urethane printed circuit board coatings. This unique solvent will completely dissolve these tough coatings yet not attack most epoxy-glass substrates and components.

Applications

1. Dynasolve 190 is recommended where selective dissolving at room temperature is required and where a flammable solvent can be utilized. Uresolve Plus SG and the Dynasolve 700 series should be considered where safer solvents are required and selectivity is not as critical. In addition, the Dynasolve 200 series should be considered for dissolving of silicones.
2. Dynasolve 190 will not attack aluminum or aluminum alloys (with addition of ½% Ethyl Silicate), electroless nickel, stainless steel or chromium, gold, silver plating and solder.
3. Dynasolve 190 will not attack Kynar, Teflon, polyethylene or many vinyl-coated wires. It may cause surface discoloration of irradiated Kynar wire and certain vinyl wire insulations. Other plastic materials not affected are epoxy (amine cured), diallyl phthalate, phenolic, neoprene, and butyl and polysulfide rubbers. It will attack anhydride cured epoxy coatings and many magnet wire coatings.

Specifications

Color:	Blue
Specific Gravity:	0.84
Boiling Point:	149°F
Flash Point:	52°F (TCC)

Directions For Use

1. Pour solvent into a polyethylene, glass, tinned iron or stainless steel container.
2. Immerse the board in solution and cover the container to limit evaporation of the solvent. Thin (.010") silicone coatings will dissolve in 16 to 24 hours; urethane coatings in 4 to 8 hours. Agitation of the solution will decrease the time by as much as 50%. Thicker coatings will require longer soaking. After coating is dissolved, wash in IPA, methanol or water. If milky residue remains, dissolving action is not complete and board should be immersed in Dynasolve 190 again.
3. For removal of coatings from ceramic or metal substrates where heat can be tolerated and faster action is necessary, we recommend Uresolve Plus SG and the Dynasolve 700 series. At 200°F, a 0.010" thick coating will dissolve within 30 minutes.

Caution and Warnings

Dynasolve 190 contains powerful organic solvents. It is harmful if inhaled or swallowed. Avoid breathing vapors or mist. Keep away from heat and flame. Avoid contact with eyes and skin. Wear gloves, safety goggles, and protective clothing when handling. Use with adequate ventilation. Refer to MSDS before use, for disposal, or additional safe handling.